

Structure	:	Silicon Monolithic Integrated Circuit
Product name	:	Dual Video Amplifier
Туре	:	BD7628FVM
Package	:	MSOP8
Features	:	 Wide operating voltage range 75Ω video line driven Low supply current

4) MSOP8 small package (4.0mm × 2.9mm × 0.9mm)

OAbsolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Positive supply voltage	VCC	+10.0	V
Negative supply voltage	VEE	-10.0	V
Power dissipation	Pd	590* ¹	mW
Input voltage range	V _{IN}	VEE-0.2V ~ VCC+0.2V	V
Operating temperature	Topr	−40°C ~ +85°C	C°
Storage temperature	Tstg	−55°C ~ +150°C	C°

*1 For operation above 25°C free-air temperature, power dissipation is decreasing 4.7mW/°C in case mounting the ROHM standard application board (70mm × 70mm × 1.6mm)

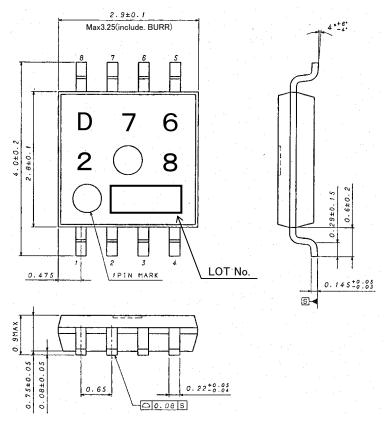
OOperating voltage range (Ta=25°C)

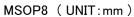
Parameter	Symbol	Min	Тур	Max	Unit
Positive supply voltage	VCC	+2.0	+5.0	+6.0	V
Negative supply voltage	VEE	-6.0	-5.0	-2.0	V

* This product is not designed for protection against radioactive rays.

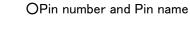


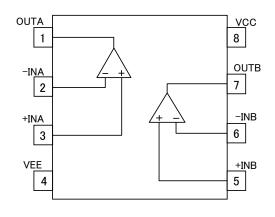
OExternal dimensions and label codes





OBlock diagram





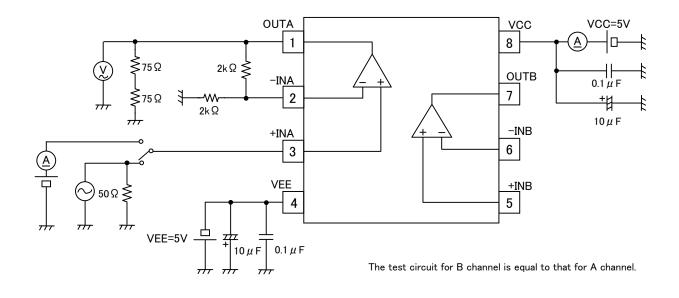
Pin NO.	Pin name	Pin NO.	Pin name
1	OUTA	5	VCC
2	-INA	6	OUTB
3	+INA	7	-INB
4	VEE	8	+INB



OElectrical characteristics (Unless otherwise specified, Ta= 25°C, VCC=5.0V, VEE=-5.0V	()
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Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Circuit current	ICC	-	16.7	23.0	mA	No Signal
Input bias current	I _{IB}	_	_	6	uA	Vin=0.0V
Maximum output voltage	V _{OM}	5.0	5.7	-	Vpp	DC Voltage
Voltage gain	Gv	5.6	5.9	6.2	dB	Vin=1.0Vpp, f=1MHz
Frequency characteristics	G _F	-2.0	-0.1	1.0	dB	Vin=1.0Vpp, f=1MHz/10MHz
Cross talk	C _T	_	-63	-50	dB	Vin=1.0Vpp, f=4.43MHz

OTest Circuit Diagrams





•Cautions for use

(1) Absolute maximum ratings

If the absolute maximum ratings for applied voltage and/or operation temperature are exceeded, LSI damage may result. Therefore, do not apply voltage or use in a temperature that exceeds these absolute maximum ratings. If it is possible that absolute maximum ratings will be exceeded, use a physical safety device such as a fuse and make sure that no conditions that might exceed the absolute maximum ratings will be applied to the LSI IC.

(2) Thermal design

The thermal design should be done using an ample margin that takes into consideration the allowable dissipation under actual use conditions.

(3) Shorts between pins and mounting errors

When mounting LSI ICs onto the circuit board, make sure each LSI's orientation and position is correct. The ICs may become damaged if they are not mounted correctly when the power is turned on. Similarly, damage may also result if a short occurs, such as when a foreign object is positioned between pins in an IC, or between a pin and a power supply or GND connection.

(4) Operation in strong electromagnetic fieldWhen used within a strong electromagnetic field, evaluate carefully to avoid the risk of operation faults.

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